

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q78657

Hien Boon TAN , et al.

Appln. No.: 10/581,395

Group Art Unit: 2818

Confirmation No.: 3868

Examiner: David J GOODWIN

Filed: August 14, 2008

For: CHIP SCALE PACKAGE AND METHOD OF ASSEMBLING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.111

MAIL STOP AMENDMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated December 13, 2010, please amend the above-identified application as follows on the accompanying pages.

TABLE OF CONTENTS

AMENDMENTS TO THE CLAIMS.....	2
REMARKS.....	7